



Description

JMG N-channel Enhancement Mode Power MOSFET

Features

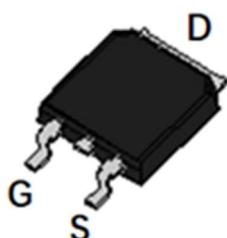
- 150V,20A
- $R_{DS(ON)} < 100m\Omega$ @ $V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

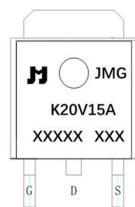
- Load Switch
- PWM Application
- Power management



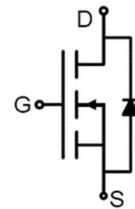
100% UIS TESTED!
100% ΔV_{ds} TESTED!



TO-252(DPAK) top view



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
JMGK20V15A	JMGK20V15A	TAPING	TO-252	13inch	2500	25000

Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		150	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current		$T_c = 25^\circ C$	A
			$T_c = 100^\circ C$	A
I_{DM}	Pulsed Drain Current ^{note1}		80	A
P_D	Power Dissipation	$T_c = 25^\circ C$	89.2	W
R_{eJC}	Thermal Resistance, Junction to Case		1.4	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	150	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=150\text{V}, V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2	-	4	V
$R_{DS(\text{on})}$	Static Drain-Source on-Resistance note2	$V_{GS}=10\text{V}, I_D=10\text{A}$	-	70	100	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=100\text{KHz}$	-	1070	-	pF
C_{oss}	Output Capacitance		-	230	-	pF
C_{rss}	Reverse Transfer Capacitance		-	9	-	pF
Q_g	Total Gate Charge	$V_{DS}=25\text{V}, I_D=5\text{A}, V_{GS}=10\text{V}$	-	22	-	nC
Q_{gs}	Gate-Source Charge		-	6	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	7.7	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=50\text{V}, I_D=5\text{A}, R_{GEN}=2\Omega, V_{GS}=10\text{V}$	-	10	-	ns
t_r	Turn-on Rise Time		-	33	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	27	-	ns
t_f	Turn-off Fall Time		-	26	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	20	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	80	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}, I_s=10\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$I_F=14\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	130	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	770	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

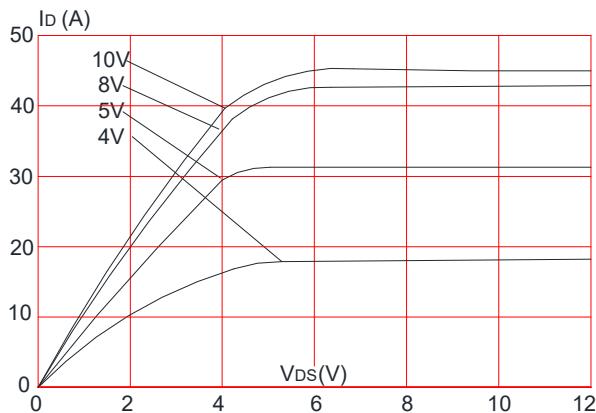


Figure 2: Typical Transfer Characteristics

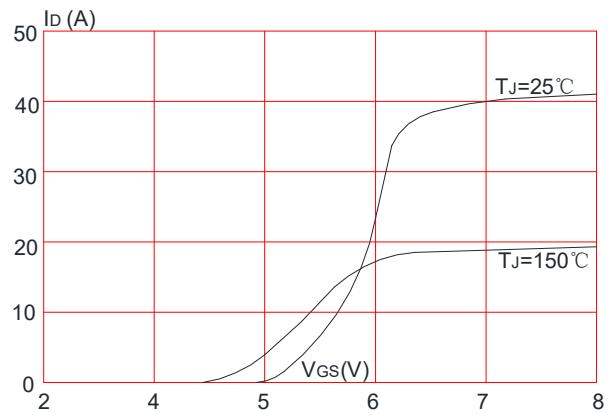


Figure 3: On-resistance vs. Drain Current

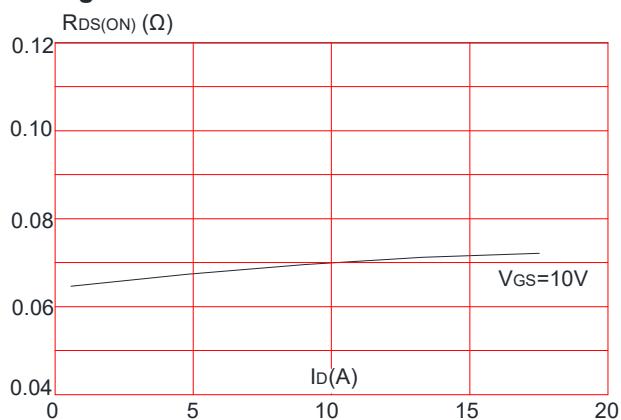


Figure 4: Body Diode Characteristics

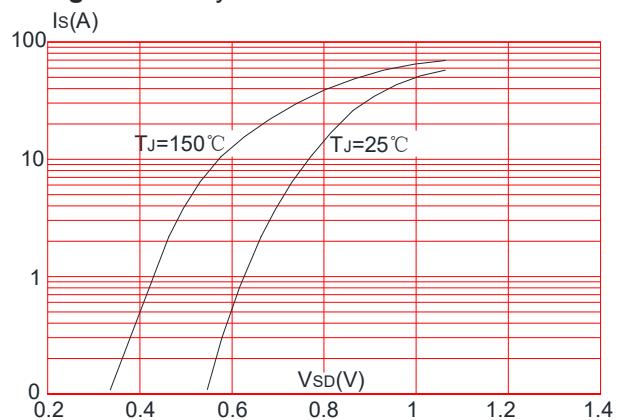


Figure 5: Gate Charge Characteristics

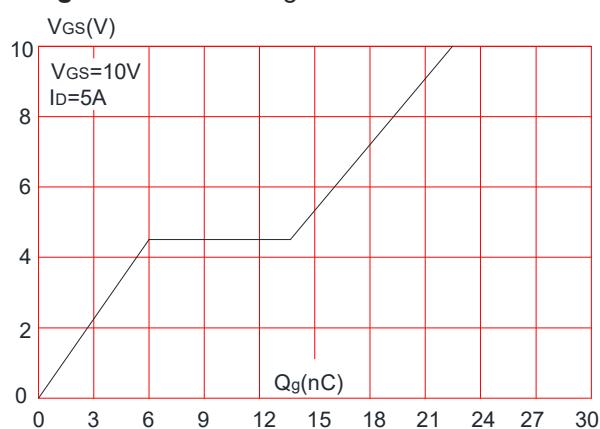


Figure 6: Capacitance Characteristics

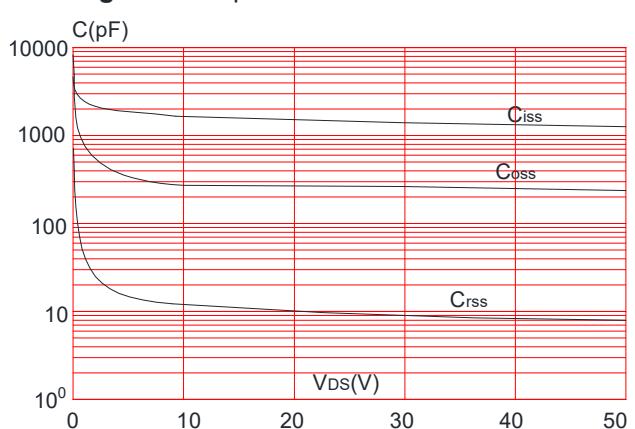


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

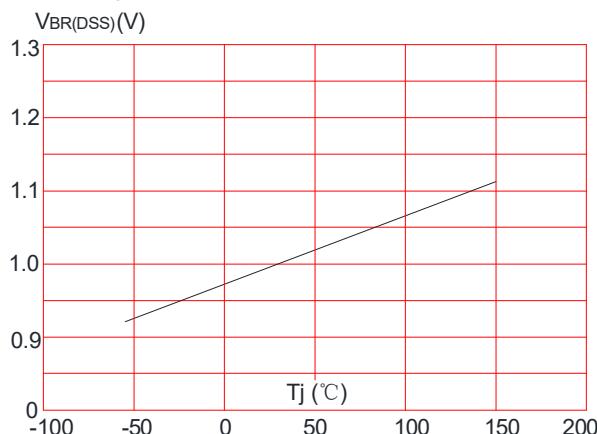


Figure 9: Maximum Safe Operating Area

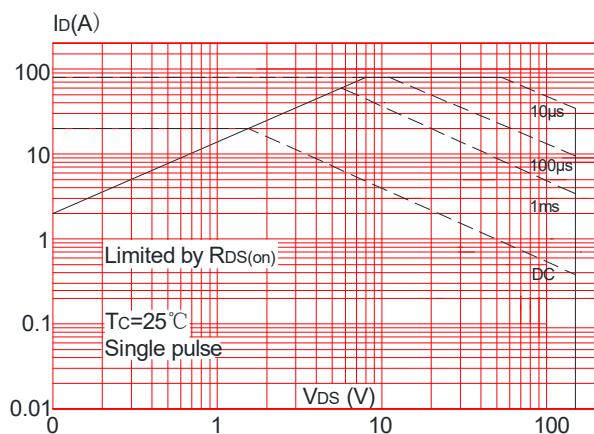


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

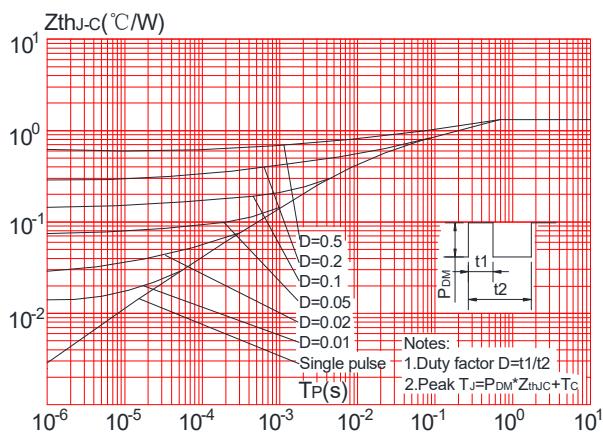


Figure 8: Normalized on Resistance vs. Junction Temperature

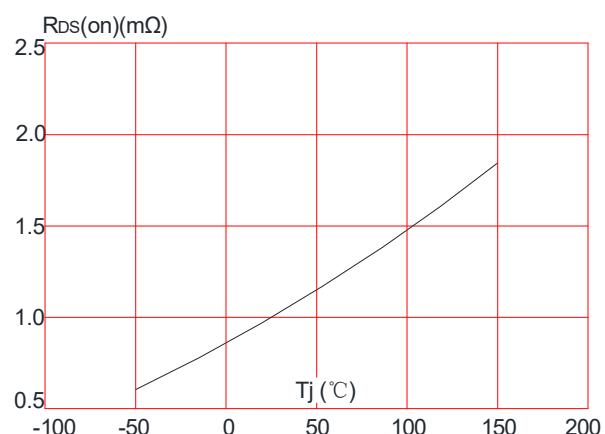
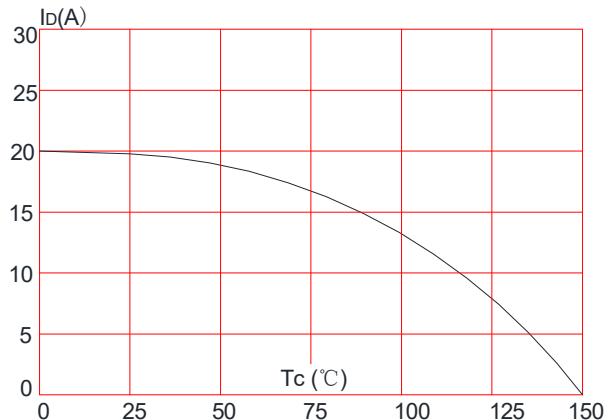


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Test Circuit

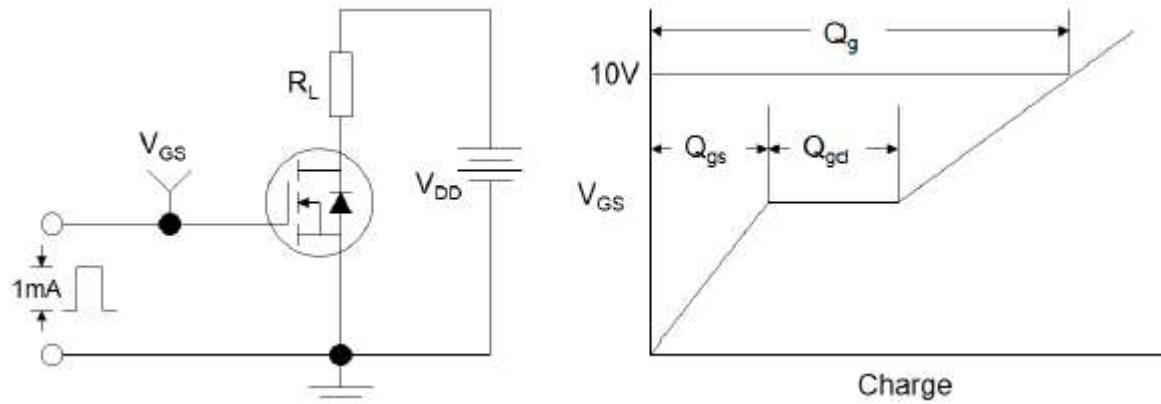


Figure1:Gate Charge Test Circuit & Waveform

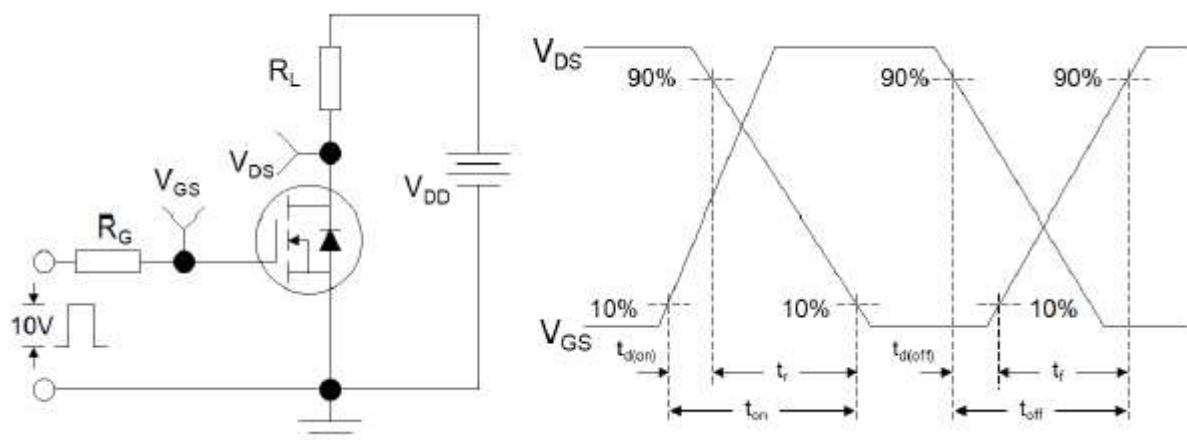


Figure 2: Resistive Switching Test Circuit & Waveforms

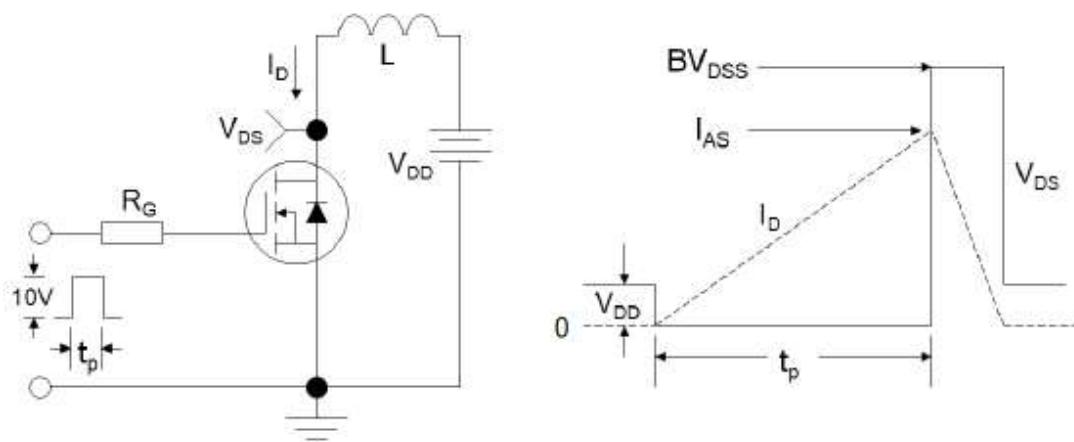
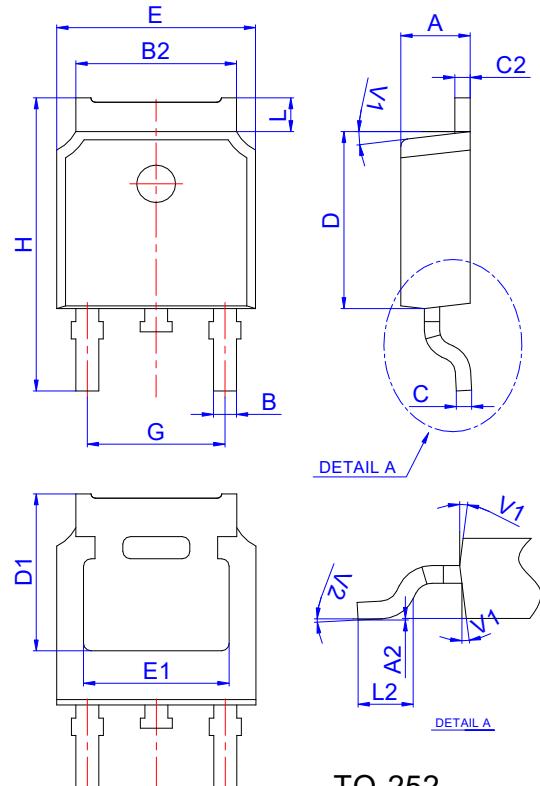


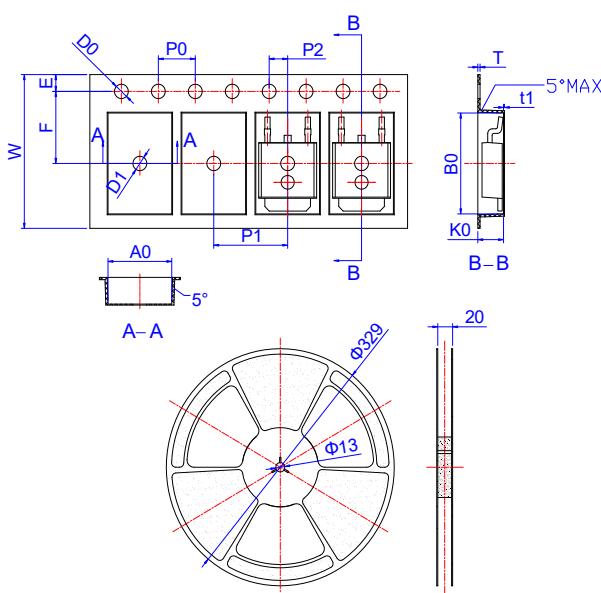
Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10			2.50	0.083	
A2	0			0.10	0	
B	0.66			0.86	0.026	
B2	5.18			5.48	0.202	
C	0.40			0.60	0.016	
C2	0.44			0.58	0.017	
D	5.90			6.30	0.232	
D1	5.30REF			0.209REF		
E	6.40			6.80	0.252	
E1	4.63				0.182	
G	4.47			4.67	0.176	
H	9.50			10.70	0.374	
L	1.09			1.21	0.043	
L2	1.35			1.65	0.053	
V1		7°				7°
V2	0°			6°	0°	
						6°

Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24			0.27	0.009	
t1	0.10				0.004	
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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